

## AMENDMENT TRANSMITTAL LETTER (Large Entity)

Applicant(s): Ray et al.

Docket No.

END920010002US1

Serial No.  
09/779,812Filing Date  
2/8/01Examiner  
Nguyen, Ha TGroup Art Unit  
2812  
RECEIVED  
APR 25 2002  
2800 MAIL ROOM

Invention: LEAD-FREE SOLDER STRUCTURE AND METHOD FOR HIGH FATIGUE LIFE

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

## CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	33 -	30 =	3	x \$18.00	\$54.00
INDEP. CLAIMS	4 -	4 =	0	x \$84.00	\$0.00
Multiple Dependent Claims (check if applicable)		<input type="checkbox"/>			\$0.00
					TOTAL ADDITIONAL FEE FOR THIS AMENDMENT
					<b>\$54.00</b>

- No additional fee is required for amendment.
- Please charge Deposit Account No. 09-0457(IBM) in the amount of \$54.00  
A duplicate copy of this sheet is enclosed.
- A check in the amount of \_\_\_\_\_ to cover the filing fee is enclosed.
- The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 09-0457(IBM)  
A duplicate copy of this sheet is enclosed.
- Any additional filing fees required under 37 C.F.R. 1.16.
- Any patent application processing fees under 37 CFR 1.17.

Signature

Dated: 04/18/2002

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I certify that this document and fee is being deposited on 4/18/02 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Signature of Person Mailing Correspondence

cc:

Typed or Printed Name of Person Mailing Correspondence